

ABSTRACT OF THE DISCLOSURE

An electronic component is obtained by forming a primer plating layer of a material which is poorly wettable to a weld brazing material 3 on a base member 11X of a contact 11 having a terminal section 111 for brazing and a contact section 112, and then forming a finish plating layer of a material which is highly wettable to the weld brazing material on the primer plating layer. An exposed region of the poorly wettable primer plating layer is formed thereafter by selectively removing a portion of the finish plating layer at the terminal section 111 and served as an arresting region for arresting the weld brazing material 3 from creeping up and migrating along the highly wettable plating layer in brazing the terminal section 111 to the brazing pad 22 of a wiring board 2.